

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

In-De OU et al.

Serial No.: Unassigned

Filed: February 15, 2002

: Group Art Unit: Unassigned

: Examiner: Unassigned

For: **THERMALLY ENHANCED SEMICONDUCTOR BUILD-UP PACKAGE**

**INFORMATION DISCLOSURE STATEMENT**

Assistant Commissioner of Patents  
**BOX PATENT APPLICATION**  
Washington, D.C. 20231

Sir:

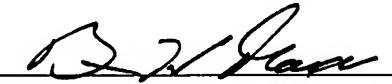
In compliance with the duty of disclosure under 37 CFR 1.56, and 37 CFR 1.97-1.98, the documents listed on the attached form PTO-1449 are hereby made of record in this patent application. Copies of the listed documents are enclosed.

As this Information Disclosure Statement is being filed prior to the mailing of the first Official Action in this application, no fee is believed due in order to have the enclosed reference considered by the Examiner and made of record in the application.

Early action on the merits of the application is earnestly solicited.

Respectfully submitted,

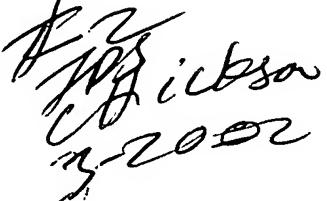
By:

  
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